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Part Number: [0879160011](#)
Status: **Active**
Description: 1.00mm (.039") Pitch DDR-2 DIMM Socket, 22.5 Degree Angle, Through Hole, 240 Circuits, 1.8V Voltage Key, 0.76µm (30µ") Gold (Au) Plating, 3.18mm (.125") Tail Length, with Off-White Latches, Lead-free

Documents:

[3D Model](#) [Product Specification PS-87916-001 \(PDF\)](#)
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification

CSA LR19980
 UL E29179

General

Product Family Memory Module Sockets
 Series [87916](#)
 Comments Latches in Off-White Color
 Component Type Memory Module
 JEDEC Outline MO-237
 Product Name DDR2 DIMM

Physical

Circuits (Loaded) 240
 Color - Resin Black, Natural
 Durability (mating cycles max) 25
 Entry Angle 22.5° Angle
 Flammability 94V-0
 Keying to Mating Part Yes
 Material - Plating Mating Gold
 Material - Plating Termination Tin
 Material - Resin High Temperature Thermoplastic
 PC Tail Length (in) 0.125 In
 PC Tail Length (mm) 3.18 mm
 PCB Locator Yes
 PCB Retention Yes
 PCB Thickness Recommended (in) 0.093 In
 PCB Thickness Recommended (mm) 2.40 mm
 Packaging Type Tray
 Pitch - Mating Interface (in) 0.039 In
 Pitch - Mating Interface (mm) 1.00 mm
 Plating min: Mating (µin) 30.4
 Plating min: Mating (µm) 0.76
 Plating min: Termination (µin) 101.6
 Plating min: Termination (µm) 2.54
 Temperature Range - Operating -55°C to +85°C
 Termination Interface: Style Through Hole

Electrical

Current - Maximum per Contact 0.5A
 Voltage - Maximum 30V
 Voltage Key 1.8V

Solder Process Data

Duration at Max. Process Temperature (seconds) 10
 Lead-free Process Capability SMC & Wave Capable (TH only)
 Max. Cycles at Max. Process Temperature 2

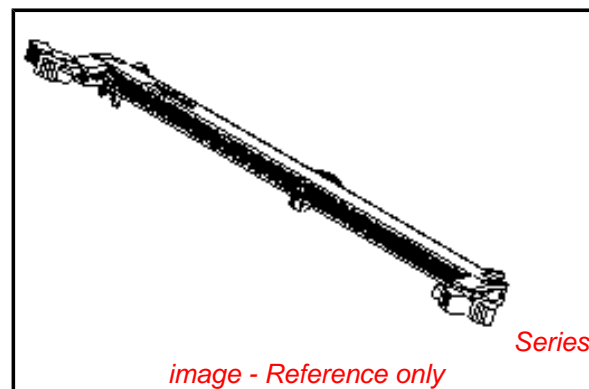


image - Reference only

EU RoHS

ELV and RoHS Compliant
REACH SVHC Contains SVHC: No
Halogen-Free Status

China RoHS



Need more information on product environmental compliance?

Email productcompliance@molex.com
 For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series

[87916Series](#)

Mates With

JEDEC standard 1.27mm modules

Process Temperature max. C

260

Material Info

Reference - Drawing Numbers

Product Specification

PS-87916-001, RPS-87916-001

Sales Drawing

SD-87916-001

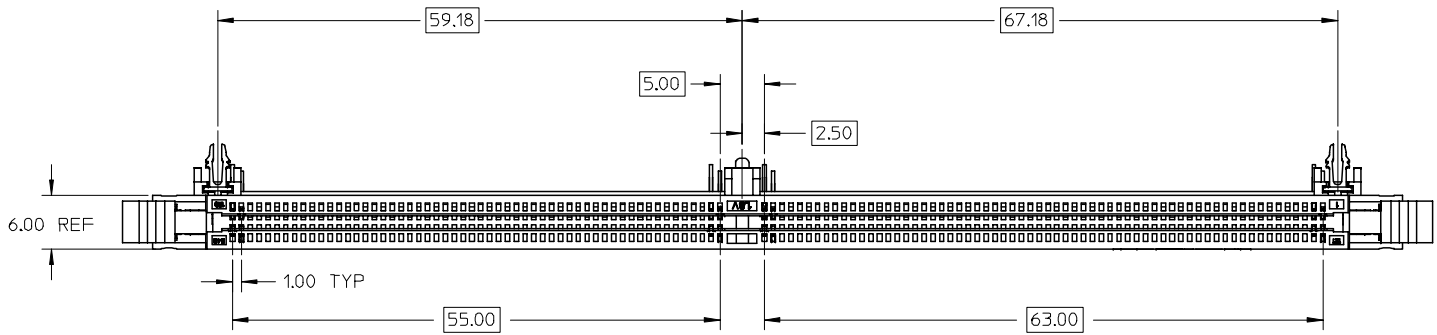
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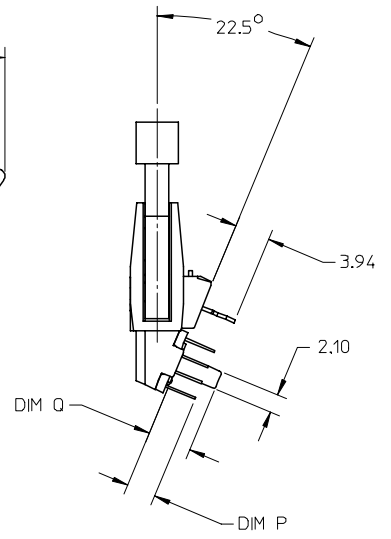
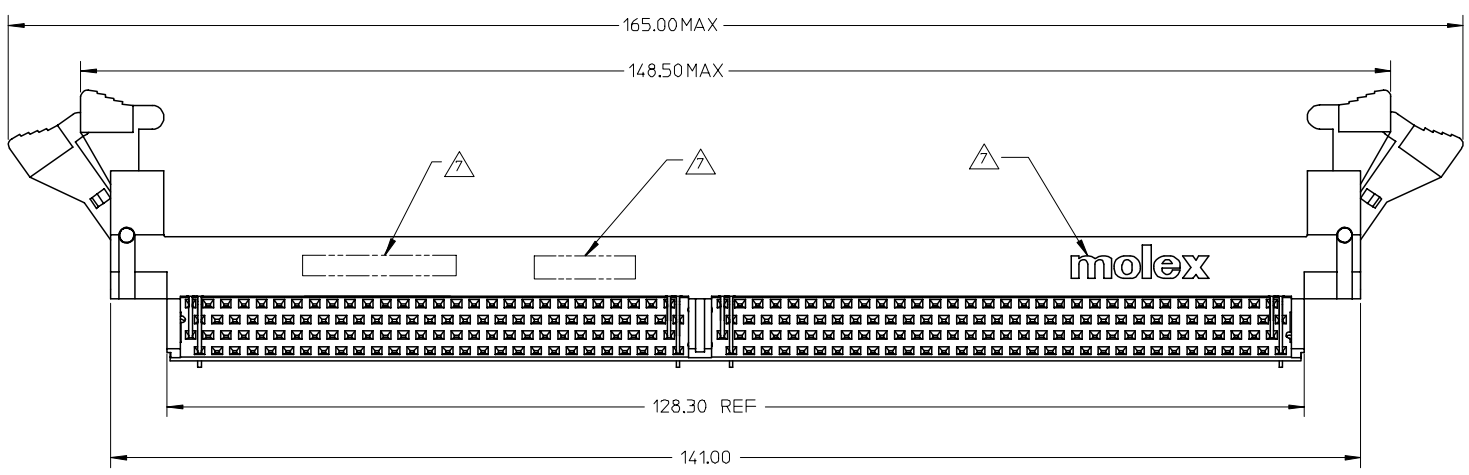


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- NOTES :
- MATERIALS : HOUSING, BASEPLATE AND LATCH.
- HIGH TEMP THERMOPLASTIC, UL94-0.
TERMINALS & FORKLOCK - COPPER ALLOY.
 - PLATING : CONTACT AREA - SEE TABLE IN SHEET 5.
SOLDERTAIL - SEE TABLE IN SHEET 5.
 - CARD SLOT ACCEPTS 1.27+/-0.10MM MODULE THICKNESS
(MEASURED OVER PC PADS).
 - REFER TO PRODUCT SPECIFICATION , PS-87916-001 FOR
PERFORMANCE SPECIFICATION.
 - RECOMMENDED MODULE CARD LAYOUT SHALL BE AS PER JEDEC MO-237.
 - PRODUCT SHALL BE PACKED IN TRAY.
- ▲ MOLEX LOGO, DATE CODE & PART NUMBER INDICATED ON HOUSING.

ADDED OPTION EC NO: S2008-0329 DRWN:CTEH CHKD:TYANG01 APPR:SHLENI 2007/10/24 2007/10/24 2007/10/25	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
				DRAWN BY JTAN		DATE 2004/05/11	TITLE DDR2 DIMM, 1.00MM PITCH 240 CKTS, 22.5 DEG			
				CHECKED BY MLONG		DATE 2004/06/11				
				APPROVED BY GGLEE		DATE 2004/06/11	MOLEX MOLEX INCORPORATED			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		DOCUMENT NO. SD-87916-001		SHEET NO. 1 OF 5		
A1				SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

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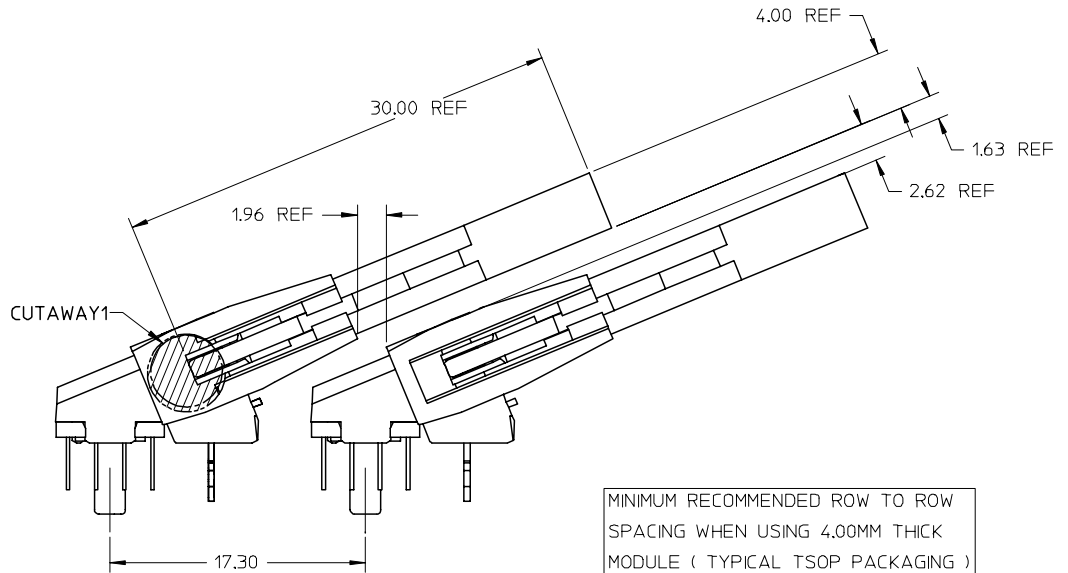
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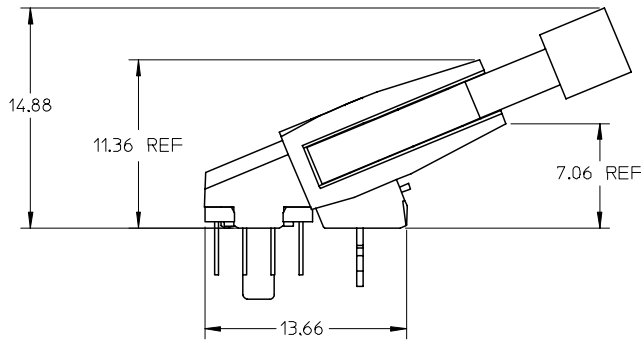
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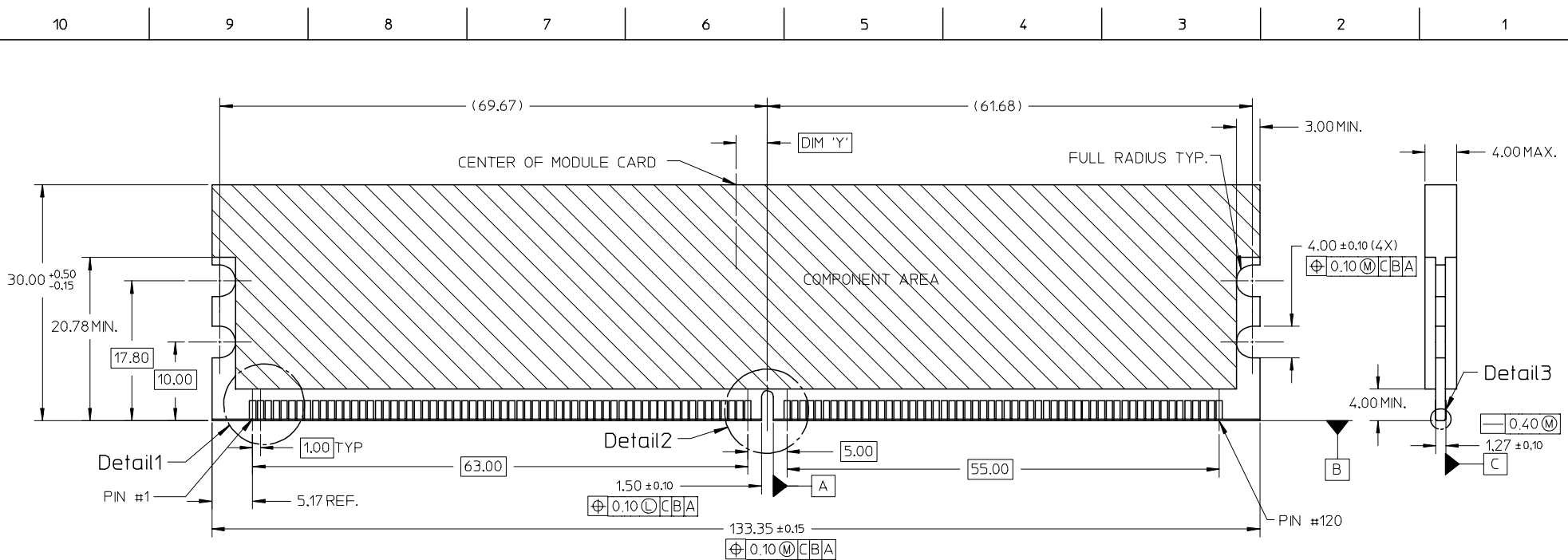


MINIMUM RECOMMENDED ROW TO ROW SPACING WHEN USING 4.00MM THICK MODULE (TYPICAL TSOP PACKAGING)

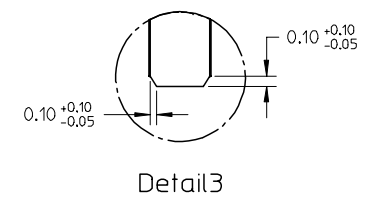
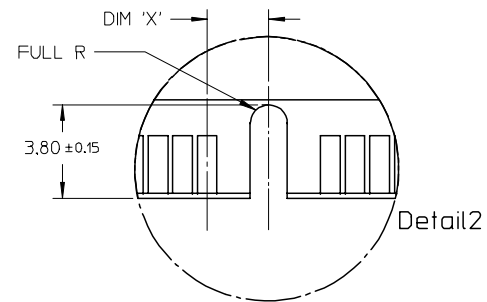
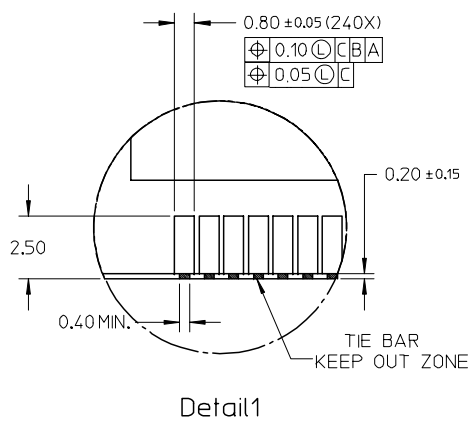


ADDED OPTION EC NO: S2008-0329 DRWN: CTEH CHKD: TYANG01 APPR: SILENI	2007/10/24 2007/10/24 2007/10/25	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION																			
			<table border="1"> <thead> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> </thead> <tbody> <tr> <td>4 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>3 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>2 PLACES</td> <td>± 0.25</td> <td>± ---</td> </tr> <tr> <td>1 PLACE</td> <td>± ---</td> <td>± ---</td> </tr> </tbody> </table>			mm	INCH	4 PLACES	± ---	± ---	3 PLACES	± ---	± ---	2 PLACES	± 0.25	± ---	1 PLACE	± ---	± ---	DRAWN BY JTAN		DATE 2004/05/11	TITLE DDR2 DIMM, 1.00MM PITCH 240 CKTS, 22.5 DEG					
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				APPROVED BY GGLEE		DATE 2004/06/11	MOLEX INCORPORATED DOCUMENT NO. SD-87916-001 SHEET NO. 2 OF 5																					
A1				MATERIAL NO.		DATE																						

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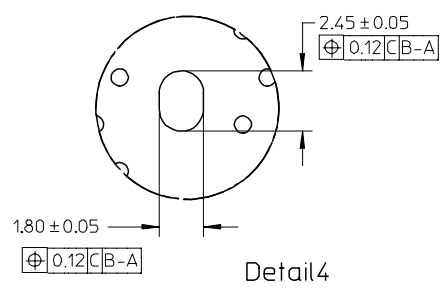
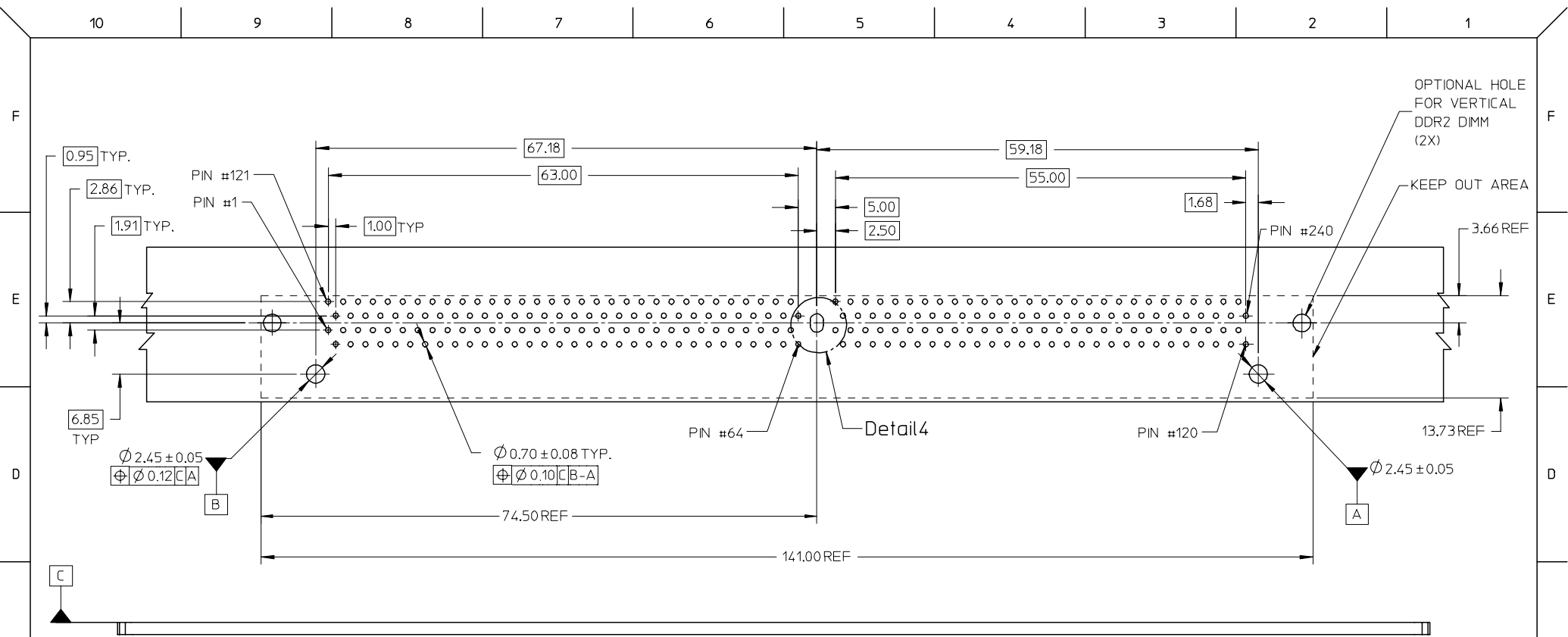


RECOMMENDED MODULE LAYOUT



KEY LOCATION	VOLTAGE	DIM 'X'	DIM 'Y'
CENTER	1.8V	2.50	4.00

ADDED OPTION EC NO: S2008-0329 DRWN: CTEH CHKD: TYANG01 APPR: SHLENI 2007/10/24 2007/10/24 2007/10/25	QUALITY SYMBOLS ▽=0 ⊕=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
				4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.25 ± --- 1 PLACE ± --- ± ---	mm INCH	DRAWN BY JTAN DATE 2004/05/11	TITLE DDR2 DIMM, 1.00MM PITCH 240 CKTS, 22.5 DEG			
				ANGULAR ± 5 °	CHECKED BY MLONG DATE 2004/06/11	APPROVED BY GGLEE DATE 2004/06/11	MOLEX INCORPORATED			
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-87916-001	SHEET NO. 3 OF 5			



ADDED OPTION	2007/10/24
EC NO: S2008-0329	2007/10/24
DRWN: CTEH	2007/10/24
CHKD: TYANG01	2007/10/25
APPR: SILENI	
REV	DESCRIPTION
A1	

QUALITY SYMBOLS	▽=0
	∇=0

GENERAL TOLERANCES (UNLESS SPECIFIED)	mm		INCH	
	4 PLACES	± ---	± ---	± ---
	3 PLACES	± ---	± ---	± ---
	2 PLACES	± 0.25	± ---	± ---
	1 PLACE	± ---	± ---	± ---
	ANGULAR ± 5 °			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				

DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
MM ONLY		NTS	METRIC	
DRAWN BY	DATE	TITLE		
JTAN	2004/05/11	DDR2 DIMM, 1.00MM PITCH		
CHECKED BY	DATE	240 CKTS, 22.5 DEG		
MLONG	2004/06/11			
APPROVED BY	DATE	MOLEX INCORPORATED		
GGLEE	2004/06/11			
MATERIAL NO.		DOCUMENT NO.	SHEET NO.	
SEE TABLE		SD-87916-001	4 OF 5	
SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
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PART NO.	VOLTAGE KEY	DIM 'P'	DIM 'O'	RECOMMENDED PCB THICKNESS	CONTACT AREA PLATING	SOLDERTAIL PLATING
87916-0001	1.8V	2.79	3.18	1.57	0.76µM/ 30µ" GOLD OVER 1.27µM/ 50µ" MIN NICKEL	2.54µM/ 100µ" MIN. TIN OVER 1.27µM/ 50µ" MIN NICKEL
87916-0011		3.18	4.83	2.36		
87916-0111		4.00		3.20		

ADDED OPTION EC NO: S2008-0329 DRWN: CTEH CHKD: TYANG01 APPR: SILENI	2007/10/24 2007/10/24 2007/10/25	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
									TITLE DDR2 DIMM, 1.00MM PITCH 240 CKTS, 22.5 DEG		
									MOLEX INCORPORATED		
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		DOCUMENT NO. SD-87916-001		SHEET NO. 5 OF 5	
A1						MATERIAL NO. GGLEE		DATE 2004/06/11		MOLEX	

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